

RL56CSMV/3 and RL56CSM/3

AnyPort™ Multi-Service Access Processor

The RL56CSMV/3 and RL56CSM/3 are members of the Conexant™ AnyPort™ family of multi-service access processors, and provide a complete solution to the transport of multiple media types between circuit-switched remote access and a variety of back-end networks (Table 1). AnyPort processors are ideally suited for the network infrastructures resulting from the convergence of voice and data networking, addressing new requirements such as Voice and Fax over packet networks, ISDN and Cellular Data, while maintaining support of traditional PSTN Data/Fax needs.

Note: RL56CSMV/3 and CSMV/3 refer to both RL56CSMV/3 and RL56CSM/3 except as noted. Any reference to voice applies only to the RL56CSMV/3.

The CSMV/3 transcends existing modem solutions by providing a complete system solution for multi-service remote access. The combined DSP/RISC architecture provides an ideal engine to run Conexant's extensive suite of field-proven modulations, echo cancellers, voice coders, and communications protocols. In addition, performing functions such as T.38, V.120, async-to-sync HDLC conversion for PPP, V.110, and synchronous HDLC for PPP on ISDN connections, in the access processor allows system designers to reduce system overhead and increase scalability.

The CSMV/3 is a low-power system providing three communication channels in a single package. Powerful and downloadable DSP-based data pumps employ on-chip SRAM to allow upgrades to future voice and communication modulation schemes. An advanced RISC microcontroller manages three data pumps simultaneously. An innovative host interface to the Multi-Service Access Processor system uses a shared SDRAM memory to increase data throughput while reducing system cost and space. A programmable time slot selection feature provides direct digital connection to a T1/E1/PRI framing device.

A 35mm BGA package houses the CSMV/3 with extra balls available for thermal vias to minimize heat. A built-in phase lock loop (PLL) minimizes board noise while easing design. A quick-wake, sleep mode further reduces the power of this +3.3V access processor system.

Features

Generic

- Three access channels in one package
- +3.3V operation with +5V tolerant inputs
- Downloadable controller firmware and data pump code
- Advanced RISC Machines (ARM) architecture
- Low-power sleep mode with quick wake
- Glueless interface to Bt8370 T1/E1/PRI framer with time slot selection
- Built-in phase lock loop (PLL)

Signaling

- DTMF detection and generation
- Multi-frequency tone support for legacy network equipment (R1 and R2)

Data

- Data modem modes
 - PSTN: ITU-T V.90, K56flex, K56Plus, V.34 (33.6 kbps), V.FC, V.32 bis, V.32, V.22 bis, V.22A/B, V.23, and V.21; Bell 212A and 103
 - ISDN: 64/56 kbps ISDN Basic Rate Interface B Channel HDLC control, or data pass-through mode for HDLC processing elsewhere in the central site system
- Internal error correction and data compression (ECC)
 - V.42 LAPM and MNP 2-4 error correction
 - V.42 bis and MNP 5 data compression
 - MNP 10EC™ enhanced cellular
- Async/sync HDLC conversion
- V.120 ISDN data
- V.110 cellular data
- LAP-B X.75

Voice (RL56CSMV/3 only)

- Baseline configuration:
 - G.723.1 and G.723.1 Annex A
 - G.711 μ -law and A-law
 - G.729 Annex A and Annex B
 - G.168 128 ms Network Echo Canceller
- Patented robust jitter buffer
- Voice API using Mailbox Messages

FAX

- Fax modem send and receive rates up to 14.4 kbps
- V.17, V.33, V.29, V.27 ter, and V.21 channel 2, Group 3, T.30 protocol and Class 1, 2 supported
- T.38 real-time fax protocol

Communications software-compatible AT commands

Table 1. RL56CSMV/3 Family Models and Functions

Model/Order/Part Numbers		Supported Functions		
Marketing Model Number	Part Number (340-Pin BGA)	Data	Fax	Voice
RL56CSM/3	R7138-94	Yes	Yes	No
RL56CSMV/3	R7178-24	Yes	Yes	Yes

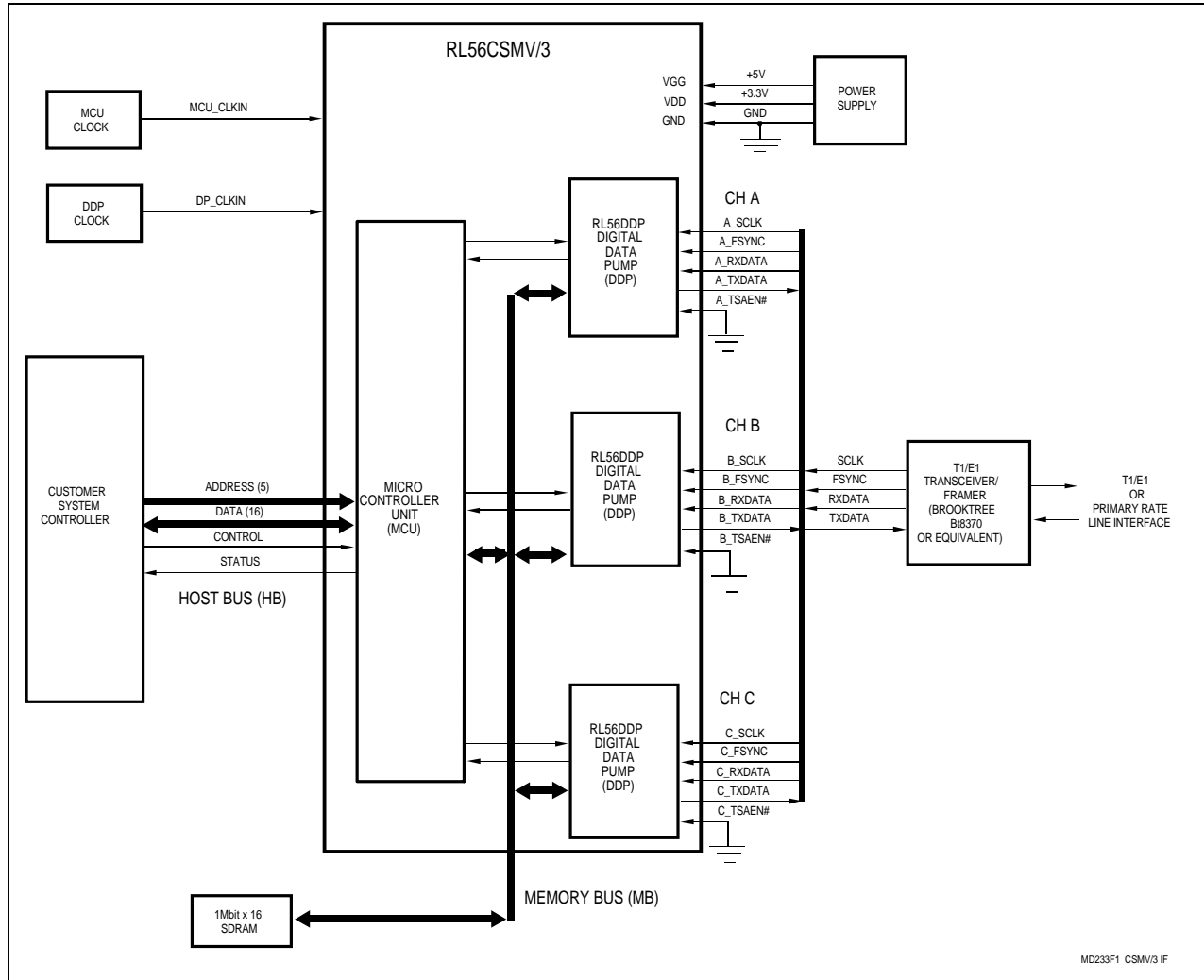


Figure 1. RL56CSMV/3 Implementation Example Block Diagram

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Technical Specifications

General Description

The CSMV/3 provides the processing core for three channels of a central site Remote Access Server supporting high speed T1/E1/PRI digital lines. The OEM adds two oscillators, SDRAM, and discrete components to complete the Multi-Service Access Processor system.

The access processor includes a full-featured, self-contained data/fax/Voice modem solution shown in Figure 1. Data modem handshake, fax modem protocol, voice codecs, and ISDN data connection functions are supported and controlled through the AT command set.

Digital Data Pump (DDP)

The DDP is a +3.3V Conexant data pump supporting PSTN data/fax modem operation, ISDN B Channel call termination mode, and voice coding/decoding. The DDP executes internal code including downloadable modules from on-chip memory.

Digital data transfers serially between the T1/E1 framer device and the DDP at a data rate up to 8.192 Mbps. The T1/E1 framing device provides a strobe signal and the DDP TSA logic detects where the data for the channel starts in the serial TDM data stream using a programmable counter. The DDP performs PCM μ -law or A-law conversion and synchronizes with an external network clock.

ARM Microcontroller (MCU)

The ARM MCU performs the command processing and interfaces to the central site system controller via a 16-bit parallel host interface. Two 64-word deep FIFOs are used for improved data throughput between the access processor and system controller. This single powerful RISC processor controls three separate channels. A SDRAM loader is available to support download from the central site system controller on startup, if desired.

Access Processor Operation

In data modem modes, each channel can independently connect to PSTN data modems at rates up to 56 kbps or ISDN terminal adapters at rates up to 64 kbps. A downloadable architecture allows for software download. For PSTN modems, complete handshake and data rate negotiations are performed. By optimizing the modem configuration for line conditions, the DDP can connect at the highest data rate that the channel can support from 56 kbps to 300 bps with automatic fallback. Automode operation in V.34 is provided in accordance with PN3320 and in V.32 bis in accordance with PN2330. All tone and pattern detection functions required by the applicable ITU or Bell standard are supported. Asynchronous to

synchronous conversion is supported inside the controller to ease PPP processing in PSTN data mode.

When the remote end is an ISDN terminal adapter, the CSMV/3 provides HDLC control including HDLC Flag generation/detection, bit stuffing/extraction, and CRC generation/checking. V.120, V.110, and LAP-B X.75 are also supported. V.120 is a standard for encapsulating asynchronous data communications traffic into ISDN data streams.

In fax modem mode, the CSMV/3 supports Group 3 facsimile send and receive speeds of 14400, 12000, 9600, 7200, 4800, and 2400 bps Fax modem modes support T.30 and T.38 fax requirements. Fax data transmission and reception performed by the access processor are controlled and monitored through the EIA-578 Class 1 and Class 2 command interface. Both transmit and receive fax data are buffered within the access processor.

In Voice mode, the CSMV/3 encodes PCM audio data from the line into Real-Time Protocol (RTP) packets for the Host, and decodes RTP packets from the Host, to output PCM audio data to the line. In Voice mode, DTMF digits can be detected and transmitted, and a Voice Activity Detector can be enabled.

Access Processor Firmware

Access processor firmware performs processing of general modem control, command sets, error correction and data compression, fax class 1 and class 2, voice coding and decoding (optional), and central site system controller interface functions.

The firmware is provided in object code form for executing from external SDRAM after download on startup using the ROM-coded Boot Loader. Equipment designers can add their own functions in firmware using commonly available development tools and the C programming language.

Hardware Interface Signals

The RL56CSMV/3 interface is illustrated in Figure 2.

The 340-pin BGA package identifying pin locations for the RL56CSMV/3 is shown in Figure 3.

The RL56CSMV/3 pin signals in the 340-pin BGA are listed by location in Table 2 and by interface in Table 3.

Additional Information

Additional information is described in the RL56CSMV/3 and RL56CSM/3 AnyPort Multi-Service Access Processor Hardware Interface Description (Order No. 1137), the RL56DDP Designer's Guide (Order No. 1141), the CSM/3 and CSMV/3 AnyPort™ Multi-Service Access Processor Software Interface Description (Order No. 1148), and the Command Reference Manual (Order No. 1195).

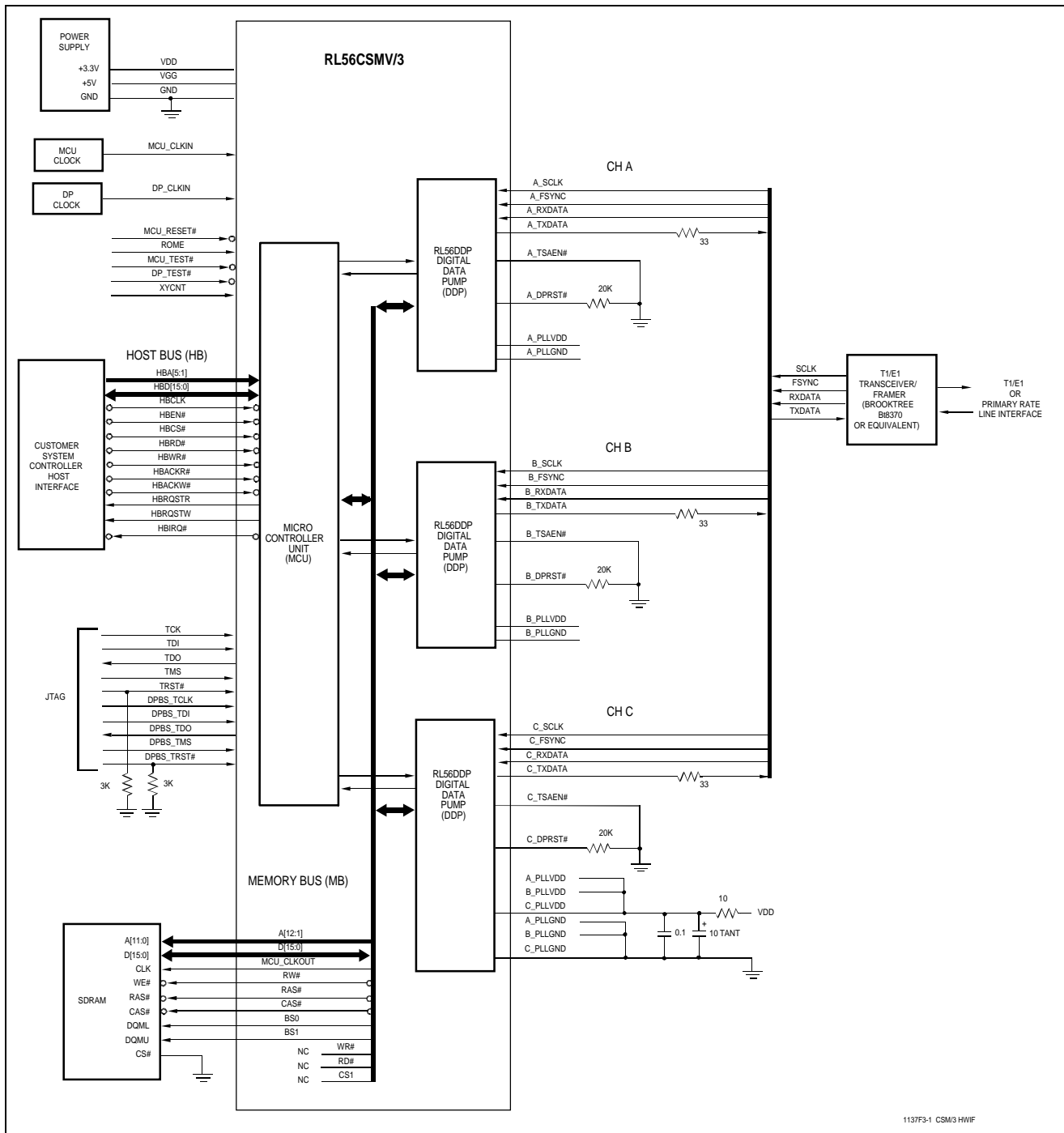


Figure 2. RL56CSMV/3 Hardware Interface Signals

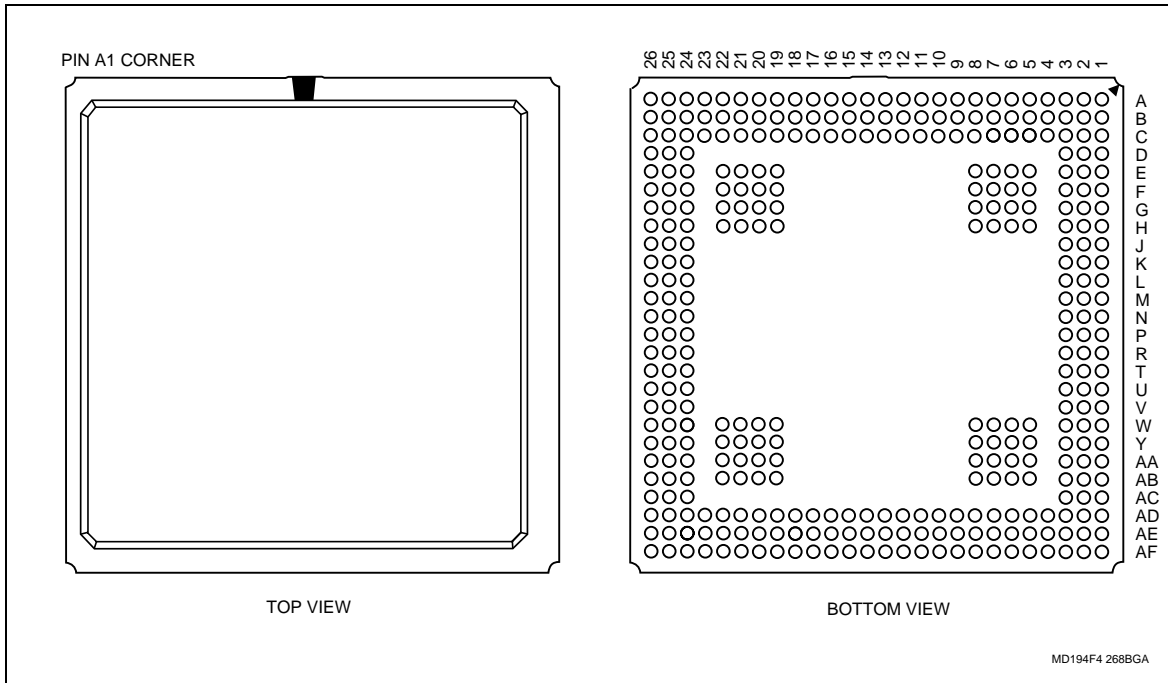


Figure 3. 340-Pin BGA Package

Table 2. RL56CSMV/3 Pin Signals by Pin Location

Table Col. Table Row	1			2			3			4		
	Loc.	Signal	I/F	Loc.	Signal	I/F	Loc.	Signal	I/F	Loc.	Signal	I/F
1	A01	C_DPRST#	GND thru 20K	B25	B_DPRXCLK	TEST	F03	VDD	3.3V	K25	A_DPTXCLK	TEST
2	A02	A_DPRST#	GND thru 20K	B26	RESERVED		F05	RESERVED		K26	A_RXDATA	CH A
3	A03	B_DPRST#	GND thru 20K	C01	B_RXDATA	CH B	F06	GND	GND	L01	D9	MB
4	A04	VGG	5V	C02	RESERVED		F07	GND	GND	L02	D8	MB
5	A05	B_DPCS	TEST	C03	RESERVED		F08	GND	GND	L03	B_EYEXY	CH B
6	A06	A4	MB	C04	RESERVED		F19	GND	GND	L24	XYCNT	TEST
7	A07	A3	MB	C05	VDD	3.3V	F20	GND	GND	L25	RESERVED	
8	A08	A2	MB	C06	B_YCLK	CH B	F21	GND	GND	L26	A_TXDATA	CH A
9	A09	A1	MB	C07	B_XCLK	CH B	F22	RESERVED		M01	D12	MB
10	A10	A0	MB	C08	B_DSPRST	TEST	F24	DP_TEST#	TEST	M02	D11	MB
11	A11	D7	MB	C09	B_PLLGND	CH B	F25	RESERVED		M03	D10	MB
12	A12	D6	MB	C10	RESERVED		F26	A_EYESYNC	CH A	M24	VDD	3.3V
13	A13	D5	MB	C11	DPBS_TRST#	JTAG	G01	B_EYESYNC	CH B	M25	A_DPCS	TEST
14	A14	D0	MB	C12	VDD	3.3V	G02	RESERVED		M26	A_DSPRST	TEST
15	A15	DP_CLKIN	SYS	C13	B_DPINT	TEST	G03	B_PLLVDD	CH B	N01	D15	MB
16	A16	RESERVED		C14	RESERVED		G05	RESERVED		N02	D14	MB
17	A17	A_DPINT	TEST	C15	VDD	3.3V	G06	GND	GND	N03	D13	MB
18	A18	A_DSPINT	TEST	C16	A_PLLVDD	CH A	G07	GND	GND	N24	WR#	MB
19	A19	A_EYEXY	CH A	C17	RESERVED		G08	GND	GND	N25	A_PLLGND	CH A
20	A20	A_XCLK	CH A	C18	RESERVED		G19	GND	GND	N26	DPBS_TCLK	JTAG
21	A21	A_YCLK	CH A	C19	RESERVED		G20	GND	GND	P01	CAS#	MB
22	A22	RESERVED		C20	RESERVED		G21	GND	GND	P02	RAS#	MB
23	A23	A_TSAEN#	CH A	C21	RESERVED		G22	RESERVED		P03	MCU_CLKIN	SYS
24	A24	RESERVED		C22	RESERVED		G24	RESERVED		P24	C_DPINT	TEST
25	A25	RESERVED		C23	A_DPTXD	TEST	G25	RESERVED		P25	RD#	MB
26	A26	RESERVED		C24	VDD	3.3V	G26	A_SCLK	CH A	P26	C_EYEXY	CH C
27	B01	B_TXDATA	CH B	C25	RESERVED		H01	B_EYECLK#	CH B	R01	PA5	NA
28	B02	RESERVED		C26	RESERVED		H02	RESERVED		R02	RESERVED	
29	B03	RESERVED		D01	RESERVED		H03	B_DSPINT	TEST	R03	MCU_CLKOUT	MB
30	B04	RESERVED		D02	RESERVED		H05	RESERVED		R24	C_DPTXCLK	TEST
31	B05	RESERVED		D03	RESERVED		H06	GND	GND	R25	C_YCLK	CH C
32	B06	RESERVED		D24	VDD	3.3V	H07	GND	GND	R26	C_XCLK	CH C
33	B07	C_DPEXRST	TEST	D25	A21	MB	H08	GND	GND	T01	PA3	NA
34	B08	A_DPEXRST	TEST	D26	RESERVED		H19	GND	GND	T02	PE4	NA
35	B09	B_DPEXRST	TEST	E01	B_FSYNC	CH B	H20	GND	GND	T03	VDD	3.3V
36	B10	D4	MB	E02	RESERVED		H21	GND	GND	T24	C_DPINT	TEST
37	B11	D3	MB	E03	RESERVED		H22	RESERVED		T25	VDD	3.3V
38	B12	D2	MB	E05	RESERVED		H24	VDD	3.3V	T26	VDD	3.3V
39	B13	D1	MB	E06	RESERVED		H25	RESERVED		U01	PA7	NA
40	B14	C_DPRXD	TEST	E07	RESERVED		H26	A_FSYNC	CH A	U02	PE0	NA
41	B15	RESERVED		E08	RESERVED		J01	RESERVED		U03	VDD	3.3V
42	B16	RESERVED		E19	RESERVED		J02	B_TSAEN#	CH B	U24	VGG	5V
43	B17	RESERVED		E20	RESERVED		J03	VDD	3.3V	U25	C_TSAEN#	CH C
44	B18	A_DPRXD	TEST	E21	RESERVED		J24	RESERVED		U26	RESERVED	
45	B19	RESERVED		E22	RESERVED		J25	RESERVED		V01	PE6	NA
46	B20	RESERVED		E24	RESERVED		J26	RESERVED		V02	PE2	NA
47	B21	RESERVED		E25	RESERVED		K01	BS1	MB	V03	RESERVED	
48	B22	B_DPRXD	TEST	E26	A_EYECLK#	CH A	K02	DPBS_TDO	JTAG	V24	C_DPRXCLK	TEST
49	B23	B_DPTXD	TEST	F01	B_SCLK	CH B	K03	VDD	3.3V	V25	C_DPTXD	TEST
50	B24	B_DPTXCLK	TEST	F02	RESERVED		K24	A_DPRXCLK	TEST	V26	C_PLLVDD	CH C

Notes: RESERVED = May have internal circuit connected, no external connection allowed.

Table 2. RL56CSMV/3 Pin Signals by Pin Location (Continued)

Table Col. Row	5			6			7			8		
	Loc.	Signal	I/F	Loc.	Signal	I/F	Loc.	Signal	I/F	Loc.	Signal	I/F
1	W01	PA4	NA	AB20	RESERVED		AE13	HBA1	HB			
2	W02	PA6	NA	AB21	RESERVED		AE14	HBCKS#	HB			
3	W03	VDD	3.3V	AB22	RESERVED		AE15	HBWR#	HB			
4	W05	GND	GND	AB24	RESERVED		AE16	HBCLK	HB			
5	W06	GND	GND	AB25	C_FSYNC	CH C	AE17	HBEN#	HB			
6	W07	GND	GND	AB26	CS3	MB	AE18	A5	MB			
7	W08	GND	GND	AC01	TRST#	JTAG	AE19	A7	MB			
8	W19	GND	GND	AC02	PF3	NA	AE20	A9	MB			
9	W20	GND	GND	AC03	VDD	3.3V	AE21	A13	MB			
10	W21	GND	GND	AC24	CS0	MB	AE22	VDD	3.3V			
11	W22	RESERVED		AC25	C_TXDATA	CH C	AE23	RESERVED				
12	W24	MCU_RESET#	SYS	AC26	C_SCLK	CH C	AE24	A14	MB			
13	W25	ROME	SYS	AD01	PF7	NA	AE25	A22	MB			
14	W26	BS0	MB	AD02	TMS	JTAG	AE26	A24	MB			
15	Y01	PE1	NA	AD03	VDD	3.3V	AF01	PF4	NA			
16	Y02	PE3	NA	AD04	VDD	3.3V	AF02	PF6	NA			
17	Y03	VDD	3.3V	AD05	VDD	3.3V	AF03	TDI	JTAG			
18	Y05	GND	GND	AD06	VDD	3.3V	AF04	HBACKR#	HB			
19	Y06	GND	GND	AD07	VDD	3.3V	AF05	HBACKW#	HB			
20	Y07	GND	GND	AD08	VDD	3.3V	AF06	HBD0	HB			
21	Y08	GND	GND	AD09	VDD	3.3V	AF07	HBD2	HB			
22	Y19	GND	GND	AD10	VDD	3.3V	AF08	HBD3	HB			
23	Y20	GND	GND	AD11	VDD	3.3V	AF09	HBD10	HB			
24	Y21	GND	GND	AD12	HBD14	HB	AF10	HBD8	HB			
25	Y22	RESERVED		AD13	HBA2	HB	AF11	HBD5	HB			
26	Y24	C_EYECLK#	CH C	AD14	HBA5	HB	AF12	HBD13	HB			
27	Y25	MCU_TEST#	SYS	AD15	DPBS_TDI	JTAG	AF13	HBD11	HB			
28	Y26	CS4	MB	AD16	C_PLLGND	CH C	AF14	HBA3	HB			
29	AA01	PE5	NA	AD17	C_DSPRST	TEST	AF15	HBA4	HB			
30	AA02	PE7	NA	AD18	A12	MB	AF16	HBRD#	HB			
31	AA03	VDD	3.3V	AD19	C_DPCS	TEST	AF17	RESERVED				
32	AA05	GND	GND	AD20	A11	MB	AF18	HBIRO#	HB			
33	AA06	GND	GND	AD21	A16	MB	AF19	A6	MB			
34	AA07	GND	GND	AD22	A15	MB	AF20	DPBS_TMS	JTAG			
35	AA08	GND	GND	AD23	A20	MB	AF21	A8	MB			
36	AA19	GND	GND	AD24	RW#	MB	AF22	A10	MB			
37	AA20	GND	GND	AD25	C_RXDATA	CH C	AF23	A17	MB			
38	AA21	GND	GND	AD26	CS1	MB	AF24	A19	MB			
39	AA22	RESERVED		AE01	PF5	NA	AF25	A18	MB			
40	AA24	VGG	5V	AE02	TDO	JTAG	AF26	A23	MB			
41	AA25	C_EYESYNC	CH C	AE03	TCK	JTAG						
42	AA26	CS2	MB	AE04	HBRQSTR	HB						
43	AB01	PF0	NA	AE05	HBRQSTW	HB						
44	AB02	PF2	NA	AE06	HBD1	HB						
45	AB03	PF1	NA	AE07	HBD9	HB						
46	AB05	GND	GND	AE08	HBD4	HB						
47	AB06	GND	GND	AE09	HBD6	HB						
48	AB07	GND	GND	AE10	HBD7	HB						
49	AB08	GND	GND	AE11	HBD12	HB						
50	AB19	RESERVED		AE12	HBD15	HB						

Notes: RESERVED = May have internal circuit connected, no external connection allowed.

Table 3. RL56CSMV/3 Pin Signals by Interface

Table Col. Table Row	1			2			3			4		
	Loc.	Signal	I/F	Loc.	Signal	I/F	Loc.	Signal	I/F	Loc.	Signal	I/F
1	AE13	HBA1	HB	G01	B_EYESYNC	CH B	L02	D8	MB	K25	A_DPTXCLK	TEST
2	AD13	HBA2	HB	H01	B_EYECLK#	CH B	L01	D9	MB	C23	A_DPTXD	TEST
3	AF14	HBA3	HB	J02	B_TSAEN#	CH B	M03	D10	MB	A18	A_DSPINT	TEST
4	AF15	HBA4	HB	C07	B_XCLK	CH B	M02	D11	MB	M26	A_DSPRST	TEST
5	AD14	HBA5	HB	C06	B_YCLK	CH B	M01	D12	MB	A05	B_DPCS	TEST
6	AF06	HBD0	HB	AC26	C_SCLK	CH C	N03	D13	MB	B09	B_DPEXRST	TEST
7	AE06	HBD1	HB	AB25	C_FSYNC	CH C	N02	D14	MB	C13	B_DPINT	TEST
8	AF07	HBD2	HB	AD25	C_RXDATA	CH C	N01	D15	MB	B25	B_DPRXCLK	TEST
9	AF08	HBD3	HB	AC25	C_TXDATA	CH C	W26	BS0	MB	B22	B_DPRXD	TEST
10	AE08	HBD4	HB	V26	C_PLLVDD	CH C	K01	BS1	MB	B24	B_DPTXCLK	TEST
11	AF11	HBD5	HB	AD16	C_PLLGND	CH C	AC24	CS0	MB	B23	B_DPTXD	TEST
12	AE09	HBD6	HB	P26	C_EYEXY	CH C	AD26	CS1	MB	H03	B_DSPINT	TEST
13	AE10	HBD7	HB	AA25	C_EYESYNC	CH C	AA26	CS2	MB	C08	B_DSPRST	TEST
14	AF10	HBD8	HB	Y24	C_EYECLK#	CH C	AB26	CS3	MB	F24	DP_TEST#	TEST
15	AE07	HBD9	HB	U25	C_TSAEN#	CH C	Y26	CS4	MB	L24	XYCNT	TEST
16	AF09	HBD10	HB	R26	C_XCLK	CH C	P25	RD#	MB	A01	C_DPRST#	GND thru 20K
17	AF13	HBD11	HB	R25	C_YCLK	CH C	AD24	RW#	MB	A02	A_DPRST#	GND thru 20K
18	AE11	HBD12	HB	A10	A0	MB	N24	WR#	MB	A03	B_DPRST#	GND thru 20K
19	AF12	HBD13	HB	A09	A1	MB	P02	RAS#	MB	T01	PA3	NA
20	AD12	HBD14	HB	A08	A2	MB	P01	CAS#	MB	W01	PA4	NA
21	AE12	HBD15	HB	A07	A3	MB	R03	MCU_CLKOUT	MB	R01	PA5	NA
22	AE16	HBCLK	HB	A06	A4	MB	P03	MCU_CLKIN	SYS	W02	PA6	NA
23	AE17	HBEN#	HB	AE18	A5	MB	A15	DP_CLKIN	SYS	U01	PA7	NA
24	AE14	HBCS#	HB	AF19	A6	MB	W24	MCU_RESET#	SYS	U02	PE0	NA
25	AF16	HBRD#	HB	AE19	A7	MB	W25	ROME	SYS	Y01	PE1	NA
26	AE15	HBWR#	HB	AF21	A8	MB	Y25	MCU_TEST#	SYS	V02	PE2	NA
27	AF04	HBACKR#	HB	AE20	A9	MB	AE03	TCK	JTAG	Y02	PE3	NA
28	AF05	HBACKW#	HB	AF22	A10	MB	AF03	TDI	JTAG	T02	PE4	NA
29	AE04	HBROSTR	HB	AD20	A11	MB	AE02	TDO	JTAG	AA01	PE5	NA
30	AE05	HBROSTW	HB	AD18	A12	MB	AD02	TMS	JTAG	V01	PE6	NA
31	AF18	HBIRO#	HB	AE21	A13	MB	AC01	TRST#	JTAG	AA02	PE7	NA
32	G26	A_SCLK	CH A	AE24	A14	MB	N26	DPBS_TCLK	JTAG	AB01	PF0	NA
33	H26	A_FSYNC	CH A	AD22	A15	MB	AD15	DPBS_TDI	JTAG	AB03	PF1	NA
34	K26	A_RXDATA	CH A	AD21	A16	MB	K02	DPBS_TDO	JTAG	AB02	PF2	NA
35	L26	A_TXDATA	CH A	AF23	A17	MB	AF20	DPBS_TMS	JTAG	AC02	PF3	NA
36	C16	A_PLLVDD	CH A	AF25	A18	MB	C11	DPBS_TRST#	JTAG	AF01	PF4	NA
37	N25	A_PLLGND	CH A	AF24	A19	MB	AD19	C_DPCS	TEST	AE01	PF5	NA
38	A19	A_EYEXY	CH A	AD23	A20	MB	B07	C_DPEXRST	TEST	AF02	PF6	NA
39	F26	A_EYESYNC	CH A	D25	A21	MB	T24	C_DPINT	TEST	AD01	PF7	NA
40	E26	A_EYECLK#	CH A	AE25	A22	MB	V24	C_DPRXCLK	TEST	C05	VDD	3.3V
41	A23	A_TSAEN#	CH A	AF26	A23	MB	B14	C_DPRXD	TEST	C12	VDD	3.3V
42	A20	A_XCLK	CH A	AE26	A24	MB	R24	C_DPTXCLK	TEST	C15	VDD	3.3V
43	A21	A_YCLK	CH A	A14	D0	MB	V25	C_DPTXD	TEST	C24	VDD	3.3V
44	F01	B_SCLK	CH B	B13	D1	MB	P24	C_DSPINT	TEST	D24	VDD	3.3V
45	E01	B_FSYNC	CH B	B12	D2	MB	AD17	C_DSPRST	TEST	F03	VDD	3.3V
46	C01	B_RXDATA	CH B	B11	D3	MB	M25	A_DPCS	TEST	H24	VDD	3.3V
47	B01	B_TXDATA	CH B	B10	D4	MB	B08	A_DPEXRST	TEST	J03	VDD	3.3V
48	G03	B_PLLVDD	CH B	A13	D5	MB	A17	A_DPINT	TEST	K03	VDD	3.3V
49	C09	B_PLLGND	CH B	A12	D6	MB	K24	A_DPRXCLK	TEST	M24	VDD	3.3V
50	L03	B_EYEXY	CH B	A11	D7	MB	B18	A_DPRXD	TEST	T03	VDD	3.3V

Notes: RESERVED = May have internal circuit connected, no external connection allowed.

Table 3. RL56CSMV/3 Pin Signals by Interface (Continued)

Table Col. Row	5			6			7			8		
	Loc.	Signal	I/F	Loc.	Signal	I/F	Loc.	Signal	I/F	Loc.	Signal	I/F
1	T25	VDD	3.3V	Y20	GND	GND	C26	RESERVED				
2	T26	VDD	3.3V	Y21	GND	GND	D01	RESERVED				
3	U03	VDD	3.3V	AA05	GND	GND	D02	RESERVED				
4	W03	VDD	3.3V	AA06	GND	GND	D03	RESERVED				
5	Y03	VDD	3.3V	AA07	GND	GND	D26	RESERVED				
6	AA03	VDD	3.3V	AA08	GND	GND	E02	RESERVED				
7	AC03	VDD	3.3V	AA19	GND	GND	E03	RESERVED				
8	AD03	VDD	3.3V	AA20	GND	GND	E05	RESERVED				
9	AD04	VDD	3.3V	AA21	GND	GND	E06	RESERVED				
10	AD05	VDD	3.3V	AB05	GND	GND	E07	RESERVED				
11	AD06	VDD	3.3V	AB06	GND	GND	E08	RESERVED				
12	AD07	VDD	3.3V	AB07	GND	GND	E19	RESERVED				
13	AD08	VDD	3.3V	AB08	GND	GND	E20	RESERVED				
14	AD09	VDD	3.3V	A16	RESERVED		E21	RESERVED				
15	AD10	VDD	3.3V	A22	RESERVED		E22	RESERVED				
16	AD11	VDD	3.3V	A24	RESERVED		E24	RESERVED				
17	AE22	VDD	3.3V	A25	RESERVED		E25	RESERVED				
18	A04	VGG	5V	A26	RESERVED		F02	RESERVED				
19	U24	VGG	5V	AA22	RESERVED		F05	RESERVED				
20	AA24	VGG	5V	AB19	RESERVED		F22	RESERVED				
21	F06	GND	GND	AB20	RESERVED		F25	RESERVED				
22	F07	GND	GND	AB21	RESERVED		G02	RESERVED				
23	F08	GND	GND	AB22	RESERVED		G05	RESERVED				
24	F19	GND	GND	AB24	RESERVED		G22	RESERVED				
25	F20	GND	GND	AE23	RESERVED		G24	RESERVED				
26	F21	GND	GND	AF17	RESERVED		G25	RESERVED				
27	G06	GND	GND	B02	RESERVED		H02	RESERVED				
28	G07	GND	GND	B03	RESERVED		H05	RESERVED				
29	G08	GND	GND	B04	RESERVED		H22	RESERVED				
30	G19	GND	GND	B05	RESERVED		H25	RESERVED				
31	G20	GND	GND	B06	RESERVED		J01	RESERVED				
32	G21	GND	GND	B15	RESERVED		J24	RESERVED				
33	H06	GND	GND	B16	RESERVED		J25	RESERVED				
34	H07	GND	GND	B17	RESERVED		J26	RESERVED				
35	H08	GND	GND	B19	RESERVED		L25	RESERVED				
36	H19	GND	GND	B20	RESERVED		R02	RESERVED				
37	H20	GND	GND	B21	RESERVED		U26	RESERVED				
38	H21	GND	GND	B26	RESERVED		V03	RESERVED				
39	W05	GND	GND	C02	RESERVED		W22	RESERVED				
40	W06	GND	GND	C03	RESERVED		Y22	RESERVED				
41	W07	GND	GND	C04	RESERVED							
42	W08	GND	GND	C10	RESERVED							
43	W19	GND	GND	C14	RESERVED							
44	W20	GND	GND	C17	RESERVED							
45	W21	GND	GND	C18	RESERVED							
46	Y05	GND	GND	C19	RESERVED							
47	Y06	GND	GND	C20	RESERVED							
48	Y07	GND	GND	C21	RESERVED							
49	Y08	GND	GND	C22	RESERVED							
50	Y19	GND	GND	C25	RESERVED							

Notes: RESERVED = May have internal circuit connected, no external connection allowed.

ELECTRICAL AND ENVIRONMENTAL SPECIFICATIONS

Operating Conditions and Absolute Maximum Ratings

Operating conditions are stated in Table 4.

The absolute maximum ratings are listed in Table 5.

Table 4. Operating Conditions

Parameter	Min.	Max.	Units
VDD	+3.0	+3.6	VDC
VGG	+4.75	+5.25	VDC
Ambient Temperature (TA)	0	70	0°C

Table 5. Absolute Maximum Ratings

Parameter	Symbol	Limits	Units
Supply Voltage	VDD	-0.5 to +4.0	V
Input Voltage	V _{IN}	-0.5 to (VGG +0.5)	V
Operating Temperature Range	T _A	-0 to +70	°C
Storage Temperature Range	T _{STG}	-55 to +125	°C
Voltage Applied to Outputs in High Impedance (Off) State	V _{HZ}	-0.5 to (VGG + 0.5)	V
DC Input Clamp Current	I _{IK}	±20	mA
DC Output Clamp Current	I _{OK}	±20	mA
Static Discharge Voltage (25°C)	V _{ESD}	±2500	V
Latch-up Current (25°C)	I _{TRIG}	±300	mA
Latch-up Current (125°C)	I _{TRIG}	±150	mA
Latch-up Current (25°C)	I _{TRIG}	±400	mA
Maximum Junction Temperature	T _J	125	°C

Current and Power Requirements

The current and power requirements are listed in Table 6.

Table 6. Current and Power Requirements

Mode	DDP Clock at 28.224 MHz				DDP Clock at 45 MHz			
	Typ. Current (mA)	Max. Current (mA)	Typ. Power (mW)	Max. Power (mW)	Typ. Current (mA)	Max. Current (mA)	Typ. Power (mW)	Max. Power (mW)
RL56CSM/3 (R7138)								
Normal mode	300	305	990	1100	NA	NA	NA	NA
Sleep mode	163		540					
RL56CSMV/3 (R7178)								
Normal mode	275	280	910	1010	330	333	1090	1200
Sleep mode	152		500		152		500	

Notes:

- Current and power figures represent entire device (3 channels).
- Test Conditions: VDD = 3.3 VDC for typical values; VDD = 3.6 VDC for maximum values.
TA = 0°C to 70°C
- f = internal operating frequency: MCU = 40 MHz; DDP = 28.224 MHz (during non-G.728 modes) or 45 MHz (during G.728 mode).

BGA Thermal Characteristics

The BGA thermal characteristics are listed in Table 7.

Table 7. Thermal Characteristics

Die Name	Die Number	T _{diff} (°C)	Natural Convection Cooling			Forced Convection Cooling at 1 m/s		
			Trise (°C)	Tmax (°C)	Tcase (°C)	Trise (°C)	Tmax (°C)	Tcase (°C)
MCU	1	2.0 °C	27	97	95	23	93	91
DDP	2, 3, and 4	2.0 °C	22	92	90	17.5	87.5	85.5

Notes:

- The thermal performance of multi die BGA packages is shown by temperature rise over the ambient temperature [°C] for different devices inside the package. The maximum operating junction temperature and case temperature can be estimated as follows:

Where:

T_{ambient} = Ambient temperature (specified at 70 °C) measured 2 inches above the center of the package.

T_{diff} = Temperature difference between junction and case (specified for a given die).

Trise = Temperature rise (specified for a given die for Natural Convection and Forced Convection at 1 m/s conditions).

T_{max} = Maximum operating junction temperature = T_{ambient} + Trise [°C].

T_{case} = Case temperature = T_{max} - T_{diff} [°C].

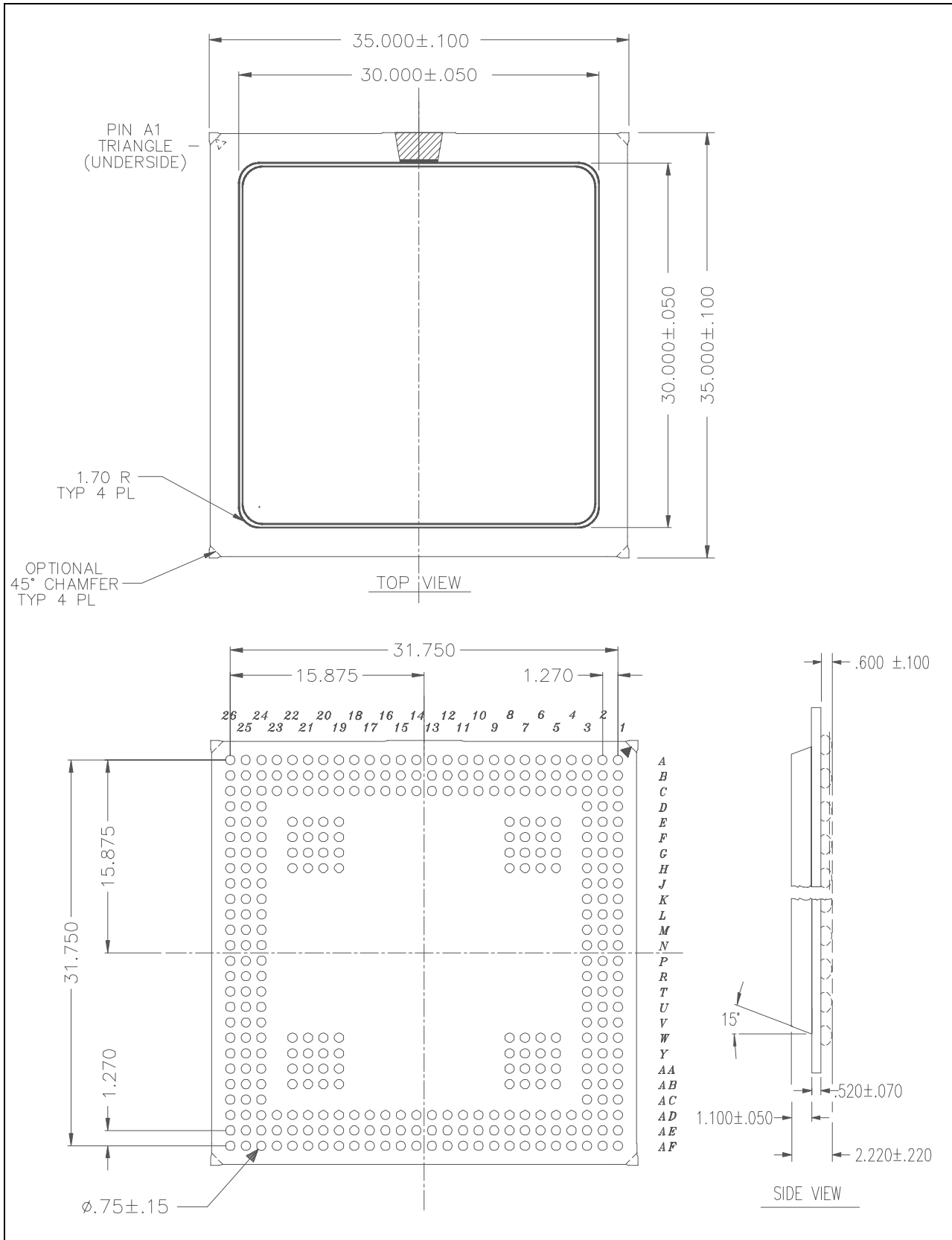
Example: Hottest Die; natural convection case with maximum T_{ambient} = 70 °C:

T_{diff} = 2.0 °C (the case temperature for the hottest die is ~2.0 °C lower than the maximum junction temperature).

T_{max} = T_{ambient} + Trise [°C] = 70 + 27 = 97 °C.

T_{case} = T_{max} - T_{diff} [°C] = 97 - 2.0 = 95 °C.

- Maximum allowable junction temperature = 125 °C.



Package Dimensions - 340-Pin BGA

REFERENCE

Table 8 identifies referenced specifications and recommendations.

Table 8. Referenced Specifications/Recommendations

Reference Number	Description
International Telecommunication Union (ITU) Recommendations	
G.168	Digital network echo cancellers
G.711	Pulse code modulation (PCM) of voice frequencies
G.723.1	Dual rate speech coder for multimedia communications transmitting at 5.3 and 6.3 kbit/s
G.723.1 Annex A	Silence compression scheme
G.723.1 Annex B	Alternative specification based on floating point arithmetic
G.726	40, 32, 24, 16 kbit/s adaptive differential pulse code modulation (ADPCM)
G.727	5-, 4-, 3- and 2-bits/sample embedded adaptive differential pulse code modulation (ADPCM)
G.728	Coding of speech at 16 kbit/s using low-delay code excited linear prediction
G.729	Coding of speech at 8 kbit/s using conjugate structure algebraic-code-excited linear-prediction (CS-ACELP)
G.729 Annex A	Reduced complexity 8 kbit/s CS-ACELP speech codec
G.729 Annex B	A silence compression scheme for G.729 optimized for terminals conforming to Recommendation V.70
Q.24	DTMF Detection
V.110	Support of data terminal equipments with V-series type interfaces by an integrated services digital network
V.120	Support by an ISDN of data terminal equipment with V-series type interfaces with provision for statistical multiplexing
V.17	A 2-wire modem for facsimile applications with rates up to 14 400 bit/s
V.21	300 bits per second duplex modem standardized for use in the general switched telephone network
V.22	1200 bits per second duplex modem standardized for use in the general switched telephone network and on point-to-point 2-wire leased telephone-type circuits
V.22 bis	2400 bits per second duplex modem using the frequency division technique standardized for use on the general switched telephone network and on point-to-point 2-wire leased telephone-type circuits
V.23	600/1200-baud modem standardized for use in the general switched telephone network
V.27 ter	4800/2400 bits per second modem standardized for use in the general switched telephone network
V.29	9600 bits per second modem standardized for use on point-to-point 4-wire leased telephone-type circuits
V.32	A family of 2-wire, duplex modems operating at data signalling rates of up to 9600 bit/s for use on the general switched telephone network and on leased telephone-type circuits
V.32 bis	A duplex modem operating at data signalling rates of up to 14 400 bit/s for use on the general switched telephone network and on leased point-to-point 2-wire telephone-type circuits
V.33	14 400 bits per second modem standardized for use on point-to-point 4-wire leased telephone-type circuits
V.34	A modem operating at data signalling rates of up to 33 600 bit/s for use on the general switched telephone network and on leased point-to-point 2-wire telephone-type circuits
V.90	A digital modem and analogue modem pair for use on the public switched telephone network (PSTN) at data signalling rates of up to 56000 bits/sec downstream and up to 33600 bits/s upstream
European Telecommunications Standards Institute (ETSI)	
ETSI SMG GSM 06.10	Full Rate voice codec.
Internet Engineering Task Force (IETF)	
ietf-avt-rtp-new-00.txt IETF, December 5, 1997	RTP: A Transport Protocol for Real-Time Applications

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